3.0x2.2mm SINGLE COLOR SURFACE MOUNT LED LAMP

AA3022EC-4.5SF HIGH EFFICIENCY RED

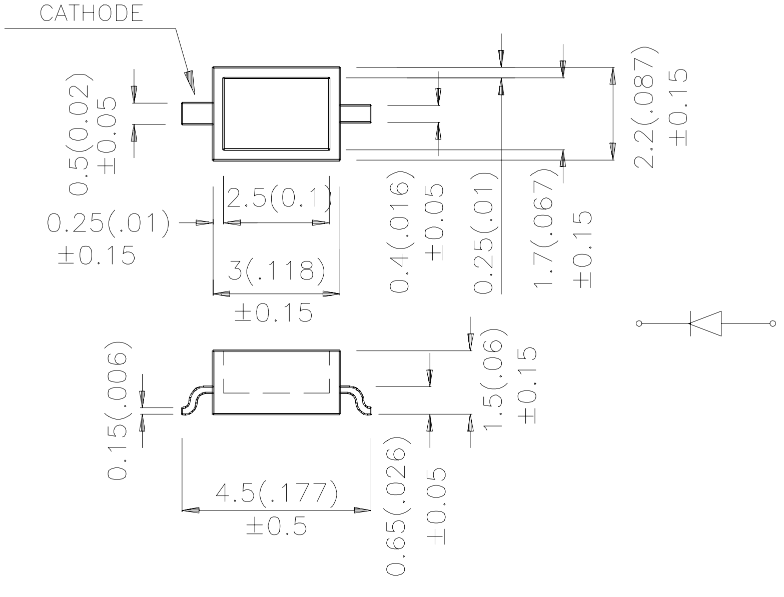
Features

- 3.0mm x 2.2mm SMT LED, 1.5mm THICKNESS.
- ULTRA-COMPACT TYPE ASSURES SPACE SAVING.
- HIGH EFFICIENCY & LOW POWER CONSUMPTION.
- PACKAGE : 1500PCS / REEL.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	$2\theta 1/2$
AA3022EC-4.5SF	HIGH EFFICIENCY RED (GaAsP / GaP)	WATER CLEAR	7	30	90°

Note:
1. $\theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

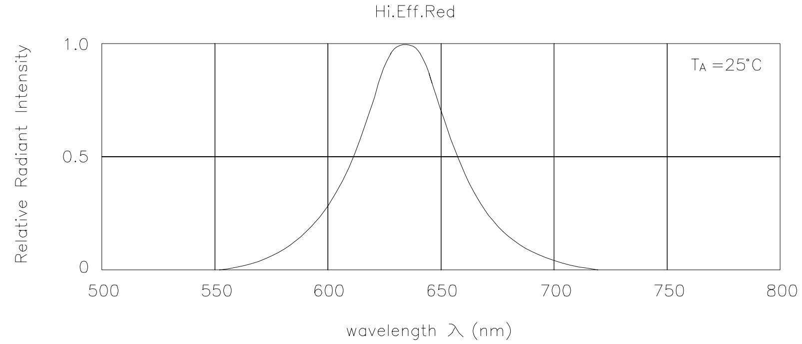
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I_F=20mA
λD	Dominate Wavelength	High Efficiency Red	625		nm	I_F=20mA
$\Delta\lambda 1/2$	Spectral Line Half-width	High Efficiency Red	45		nm	I_F=20mA
C	Capacitance	High Efficiency Red	15		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	High Efficiency Red	2.0	2.5	V	I_F=20mA
I_R	Reverse Current	High Efficiency Red		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

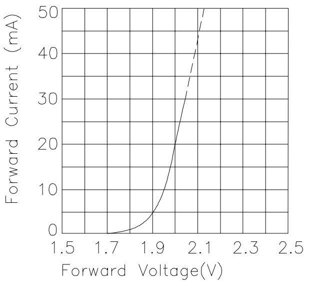
Parameter	High Efficiency Red	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

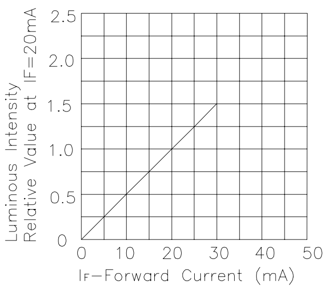


RELATIVE INTENSITY Vs. WAVELENGTH

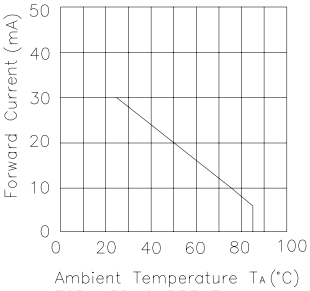
High Efficiency Red AA3022EC-4.5SF



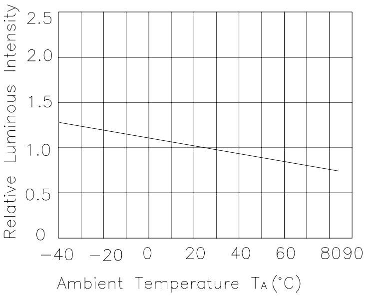
FORWARD CURRENT Vs.
FORWARD VOLTAGE



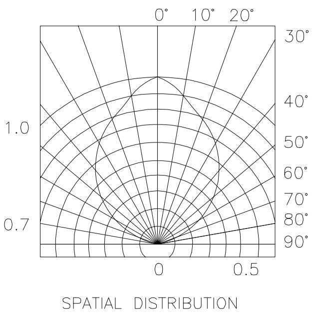
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



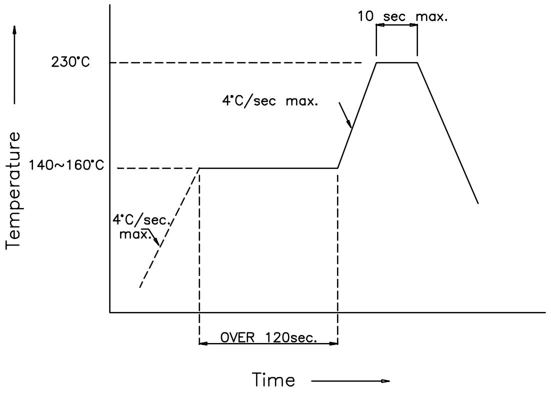
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



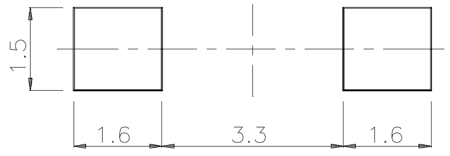
SPATIAL DISTRIBUTION

AA3022EC-4.5SF
SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern
(Units : mm)



Tape Specifications
(Units : mm)